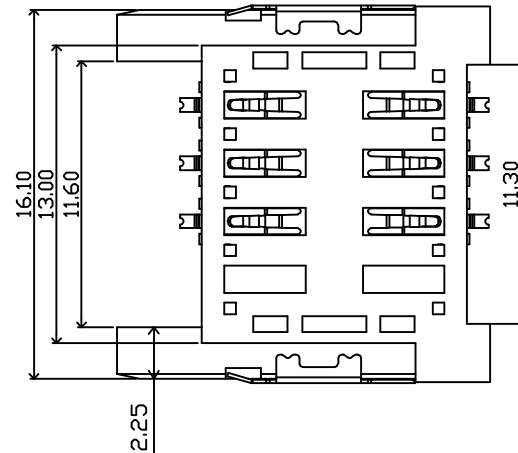


PCB LAYOUT



REVISIONS

LTR	DESCRIPTION	DATE	DWN	APVD
A	RELEASED	01Jan16	AW	WK

Remarks:

1. Material:
  - 1.1 Housing: LCP UL94V-0
  - 1.2 Terminal: Phosphor copper C5191, Half metallic tin, Gold 1u" on contact area plating, matte-Sn 100U"
  - 1.3 Shell: SUS201, nickle groud 50u", Gold 1u" at solder tail
2. Main Performance:
  - 2.1 Rated current: 0.5A
  - 2.2 Contact resistance: 50mΩ MAX
  - 2.3 Insulation resistance: 100MΩ MIN 100V DC
  - 2.4 Withstanding voltage test: 100V AC
  - 2.5 Solderability: temperature 235±5°C, time 5±0.5s
  - 2.6 Life cycle: 5000times
  - 2.7 Withstanding temperature: oven test: temperature 250±5°C, 2 minutes
  - 2.8 Operating environment: temperature: -30°C~+80°C; humidity: 80% MAX

YL004-005-XXX  
PART NUMBER

THIS DRAWING IS A CONTROLLED DOCUMENT.		DWN A. WU 01Jan2016	<b>东莞市宇亮电子有限公司</b> DONG GUAN YU LIANG ELECTRONICS CO., LTD	
DIMENSIONS: mm		CHEK S. CHIEN 01Jan2016		
TOLERANCES UNLESS OTHERWISE SPECIFIED:		APVD Abel 01Jan2016	SIM CARD 2.54MM 6P H=1.5MM 有档	
 THIRD ANGLE PROJECTION		PRODUCT SPEC —	SIZE A4	DRAWING No. Y=YL004-005
0 PLC ± 0.50 1 PLC ± 0.30 2 PLC ± 0.20 3 PLC ± 0.15 4 PLC ± - ANGLES ± 3°		WEIGHT —	CUSTOMER DRAWING	SCALE 1 : 1 SHEET 1 of 1